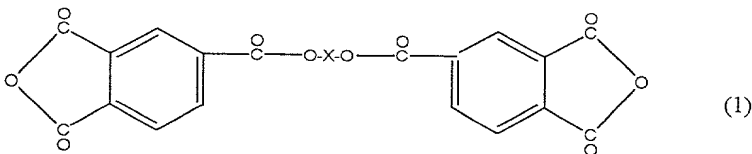


What is claimed is:

1. An HDD suspension to be obtained by processing a laminate which is constructed of an insulating resin layer and a metal foil successively formed on a stainless steel substrate and satisfies the following conditions; the insulating resin layer has plural layers of polyimides and every constituent layer of the insulating resin layer exhibits a mean etching rate of $0.5 \mu\text{m}/\text{min}$ or more by a 50% aqueous solution of potassium hydroxide at 80°C , the layers in the insulating resin layer which exist in contact with the stainless steel substrate and the metal foil are those of polyimide (B) exhibiting a glass transition temperature of 300°C or less, and the adhesive strength between the layer of polyimide (B) and either the stainless steel substrate or the metal foil is $0.5 \text{ kN}/\text{m}$ or more.

2. An HDD suspension as described in claim 1 wherein the insulating resin layer of the laminate comprises at least one layer of low-thermal-expansion polyimide (A) exhibiting a coefficient of thermal expansion of $30 \times 10^{-6}/^\circ\text{C}$ or less.

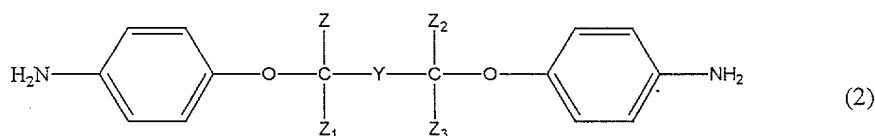
3. An HDD suspension as described in claim 1 wherein polyimide (B) constituting the insulating resin layer of the laminate is obtained by the reaction of a diamine and a tetracarboxylic acid dianhydride and 50 mol% or more of said tetracarboxylic acid dianhydride is one kind or two kinds of more of tetracarboxylic acid dianhydrides selected from pyromellitic dianhydride, 3,4,3',4'-benzophenonetetracarboxylic acid dianhydride, 3,4,3',4'-diphenylsulfonetetracarboxylic acid dianhydride and a tetracarboxylic acid dianhydride represented by the following general formula (1)



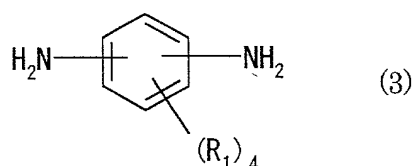
wherein X designates a linear or branched divalent aliphatic hydrocarbon group having 2-30 carbon atoms with or without substituents.

4. An HDD suspension as described in claim 1 wherein polyimide (B) constituting the insulating resin layer of the laminate is obtained by the reaction of a diamine and a tetracarboxylic acid dianhydride and 50 mol% or more of said diamine is one

kind or more of diamines selected from 1,3-bis(3-aminophenoxy)benzene, 3,4'-diaminodiphenyl ether, a diamine represented by the following general formula (2)



wherein Z, Z₁, Z₂ and Z₃ independently designate a hydrogen atom or an alkyl group with 1-3 carbon atoms and Y designates a linear or branched divalent aliphatic hydrocarbon group having 1-5 carbon atoms with or without substituents; and a diamine represented by the following general formula (3)



wherein R₁ designates independently hydrogen, an alkyl group with 1-10 carbon atoms, an alkoxy group with 1-10 carbon atoms or a halogen.

5. An HDD suspension as described in claim 1 wherein processing of the laminate comprises patterning of the insulating resin layer by wet etching as an essential step.

6. A process for manufacturing an HDD suspension which comprises utilizing a laminate constructed of an insulating resin layer and a metal foil successively formed on a stainless steel substrate and patterning the insulating resin layer of the laminate by wet etching as an essential step, said laminate satisfying the following conditions; the insulating resin layer has plural layers of polyimides and every constituent layer of the insulating resin layer exhibits a mean etching rate of 0.5 μm/min or more by a 50% aqueous solution of potassium hydroxide at 80°C, the layers in the insulating resin layer which exist in contact with the stainless steel substrate and the metal foil are those of polyimide (B) exhibiting a glass transition temperature of 300 °C or less, and the adhesive strength between the layer of polyimide (B) and either the stainless steel substrate or the metal foil is 0.5 kN/m or more.

7. A process for manufacturing an HDD suspension as described in claim 6 wherein the patterning by wet etching is performed by the use of a basic fluid exhibiting a pH of 9 or more.

8. A process for manufacturing an HDD suspension as described in claim 6 wherein the patterning by wet etching is performed in 2-1,800 seconds.

9. A process for manufacturing an HDD suspension as described in claim 6 wherein the patterning of the insulating resin layer by wet etching is performed at 20-100 °C by the use of a basic fluid.